

Amendment under 37 C.F.R. § 1.111
USSN 09/685,771

B conductive elements which electronically connect said top main surface and said bottom main surface and cover an entire side of said substrate with said top main surface and said bottom main surface.

Sub C2 10. (Twice Amended) A substrate comprising:

a part of circuit which is provided on the surface of said substrate;

R surface layers which are kept to the ground potential and cover the surface of said substrate except said part of circuit and its periphery, wherein said surface layers include a top main surface and a bottom main surface; and

conductive elements which electronically connect said top main surface and said bottom main surface and cover an entire side of said substrate with said top main surface and said bottom main surface.